

Application

Wafer scale spin-coatable B-stage die attach material



Features

- Good spin-coatability
- Good flatness after spin-coat
- Short time B-stageable (120C/10min)
- After B-staged material is stable (6months@25C)
- Good release performance from dicing film (standard and UV type).

Properties

Paste properties	Test method	SFX524A
Viscosity	CP42/10rpm	3Pa·s
Pot life	in syringe	168hr
Shelf life	-40°C	1year

Spin-coat condition		
500rpm/30sec + 1000rpm/30sec	After B-stage thickness	45 μm
500rpm/30sec + 2000rpm/30sec	After B-stage thickness	25 μm
500rpm/30sec + 4000rpm/30sec	After B-stage thickness	15 μm

B-stage properties		
B-stage condition	120°C/10min	
Pot life of after B-stage	6months/25C	
Die attaching condition	Die temperature	25~150°C
	Substrate temperature	150°C
	Pressure	0.5MPa
	Time	0.5sec

Post cure properties	Test method	SFX524A
Cure condition	RT~125°C/30min + 125°C/1hr + 125°C~165°C/30min + 165°C/2hr	
Tensile modulus	DMA25°C 0.2mmt	1500MPa
	DMA125°C 0.2mmt	500MPa
Glass transition temp.	TMA	120°C
Coefficient of thermal expansion	TMA -50°C~0°C	68ppm
	TMA 180°C~230°C	153ppm
Die share strength	2.5mm□Si to Si Post cure	27MPa
	2.5mm□Si to Si MSL1+IR260°C	23MPa

